

Design of 32Bit Carry-lookahead Adder using Constant Delay Logic

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Abstract - This paper presents an enhanced 32-bit carry lookahead (CLA) adder implementing using the constant delay (CD) logic, targeting at full-custom high-speed applications. The CD characteristic of this logic style regardless of the logic type makes it suitable in implementing complicated logic expressions such as addition. CD logic exhibits a unique characteristic where the output is pre-evaluated before the inputs from the preceding stage is ready. This feature offers performance advantage over static and dynamic domino logic styles in a single-cycle multistage circuit block. Several design considerations including timing window width adjustment and clock distribution are discussed. Using 65-nm general-purpose CMOS technology, the proposed logic demonstrates an average speed up of 94% and 56% over static and dynamic domino logic, respectively, in five different logic gates. Simulation results of 8-bit ripple carry adders show that CD logic is 39% and 23% faster than the static and dynamic-based adders, respectively. CD logic also demonstrates 39% speedup and 64% (22%) energy-delay product (EDP) reduction from static logic at 100% (10%) data activity in 32-bit carry look ahead adders. For 8-bit Wallace tree multiplier, CD logic achieves a similar speedup with at least 50% EDP reduction across all data activities.

Index Terms- Adder, constant delay (CD), feed through, high-performance logic style, pre-evaluated.

I. INTRODUCTION

HIGH-PERFORMANCE energy-efficient logic style has always been a popular research topic in the field of VLSI circuits because of the continuous demands of ever-increasing circuit operating frequency. The invention of the dynamic domino logic [Fig. 1(a)] in the 1980s is one of the answers to this request, as it allows designers to implement high-performance circuit blocks, i.e., arithmetic logic units, at an operating frequency that traditional static and pass transistor CMOS logic styles find difficult to achieve [1]. However, the performance enhancement comes with several costs, including a reduced noise margin, a problem of charge-sharing and higher power dissipation due to a higher data activity. Several variations of the dynamic domino logic, namely NP domino (NORA domino) [2], zipper domino [3], and data-driven dynamic logic (D^3L) [4], [5], have been proposed but they are never widespread in the VLSI industry [6], [7].

Compound domino logic (CDL), where dynamic and static gates alternating between each other, has become the most popular logic style in high-performance circuit blocks, i.e.

64-bit adder, in modern CPUs [8] – [11]. In this design, the output inverter is replaced with a more complex inverting static gate, i.e., NAND, such that the monotonicity requirement is satisfied while conducting complex logic operations without wasting the one inverter delay [12]. Moreover, all the dynamic stages except the first stage can be footless in CDL. This implementation, however, comes at the expense of: 1) Increased power consumption due to the possible direct path current during the precharge period; and 2) a reduced noise margin as a result of unprotected dynamic domino logic's outputs [6].

A significant research effort has been dedicated to exploring new logic styles that go beyond dynamic domino logic and CDL. In particular, source-coupled logic (SCL) [13] has shown superior performances that are difficult to achieve by any other logic styles. However, it suffers from high power dissipation due to a constant current draw, and its differential nature requires complementary signals. Pseudo-nMOS logic, which uses a single pull-up pMOS transistor, provides both high speed and low transistor count at the expense of high static power consumption as well as reduced output voltage swing. Output prediction logic (OPL) [14] has also shown superior performance in high-speed adders [15]. Nevertheless, OPL requires the generation and distribution of multiphase clock signals with small timing separations and low skews, which are difficult to achieve. While numerous high-speed logic styles have been proposed, dynamic and CDL still remain the most attractive choices when performance is the primary concern.

In recent years, a new way of logic operation, also known as feedthrough logic (FTL) [16], [17], has been proposed, which has demonstrated its high-performance capability. Consider dynamic domino logic [Fig. 1(a)], the critical path consists of nMOS logic transistors. In FTL however, the roles of the clock and logic transistors are interchanged (Section II-A) and the clock transistor is now the critical path. The first generation of FTL exhibits many shortcomings, including excessive power dissipation, and reduced noise margin. To mitigate these problems, we propose a new high-performance logic, which we call "constant delay" (CD) logic. CD logic provides a local window technique and a self-reset circuit which enable robust logic operation with minimized power consumption while maintaining FTL's speed advantage. The most distinct characteristic of CD logic from previously proposed logic styles is that the delay is, on a first-order approximation, not affected by the logic expression.¹ Unlike SCL, CD logic does not require

¹ The delay of CD logic is still a function of logic expression when all effects are considered, since a more complicated logic expression implies a larger capacitive load.

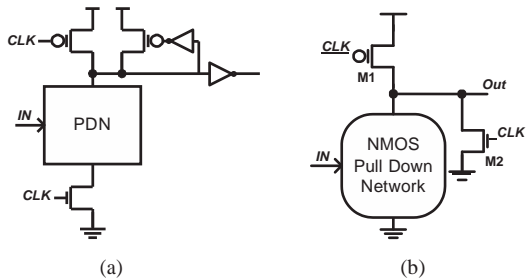


Fig. 1. Schematic of (a) dynamic domino logic with a footer transistor and (b) FTL.

complementary signals and can be easily integrated with static and dynamic domino logics. Also, CD logic does not have the problem of constant static power dissipation similar to pseudo-nMOS. Furthermore, the clock timing requirement of CD logic is not as stringent as OPL. CD logic can achieve robust operation with optimal performance as long as clock signals arrive earlier than the input signals. In this paper, we will demonstrate that: 1) CD logic outperforms other logic styles with better energy efficiency and is particularly suitable for high-performance digital blocks and 2) CD logic is robust under extreme process and temperature variations.

The rest of this paper is organized as follows. Section II reviews the history of FTL and introduces the proposed CD logic. Section III discusses the design considerations of CD logic and provides a first-order approximation of the unwanted glitch voltage. Section IV analyzes the impacts of window width on robustness and compares CD logic with other logic styles in different logic expressions. Section V demonstrates CD logic's performance advantage in single-cycle multistage digital applications such as 32-bit adders. Finally, Section VI concludes with some final remarks.

II. EVOLUTION OF CD LOGIC

A. FTL Logic

FTL logic [Fig. 1(b)] in CMOS technology was first introduced in [16] and [17]. Its basic operation is as follows: when CLK is high, the precharge period begins and Out is pulled down to GND through M2. When CLK becomes low, M1 is on, M2 is off, and the gate enters the evaluation period. If inputs (IN) are logic "1," Out enters the contention mode where M1 and transistors in the nMOS pull-down network (PDN) are conducting current simultaneously. If PDN is off, then the output quickly rises to logic "1." In this case, FTL's critical path is always a single pMOS transistor.

Despite its performance advantage, FTL suffers from reduced noise margin, excess direct path current, and nonzero nominal low output voltage, which are all caused by the contention between M1 and nMOS PDN during the evaluation period. Furthermore, cascading multiple FTL stages together to perform complicated logic evaluations is not practical. Consider a chain of inverters implemented in FTL cascaded together and driven by the same clock, as shown in Fig. 2. When CLK is low, M1 of every stage turns on, and the output of every stage begins to rise. This will result in false logic

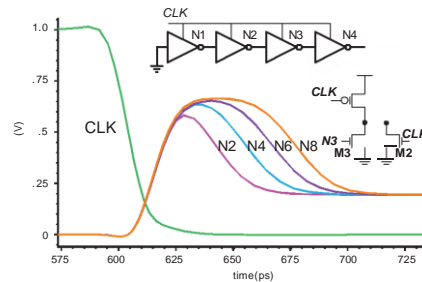


Fig. 2. Simulated unwanted glitch at different logic depths in a chain of inverters implemented with FTL.

evaluations at even numbered (i.e., 2, 4, 6, etc.,) stages since initially there is no contention between M1 and nMOS PDN because all inputs to nMOS transistors are reset to logic "0" during the reset period.

B. CD Logic

To mitigate the above-mentioned problems, CD logic is proposed with a schematic shown in Fig. 3(a). *Timing block* (TB) creates an adjustable window period to reduce the static power dissipation. *Logic Block* (LB) helps to reduce the unwanted glitch and also makes cascading CD logic feasible. A buffer implemented in CD logic with schematics of TB and LB is shown in Fig. 3(b).

1) *CD Logic Operation*: Fig. 4 depicts the corresponding CD logic timing diagram and flowchart. For simplicity, we assume that IN come from dynamic domino logic gates. When CLK is high, CD logic precharges both X and Y to GND. When CLK is low, CD logic enters the evaluation period and three scenarios can take place: namely, the contention, C-Q delay, and D-Q delay modes. The contention mode happens when CLK is low while IN remains at logic "1." In this case, X is at a nonzero voltage level which causes out to experience a temporary glitch. The duration of this glitch is determined by the local window width, which is determined by the delay between CLK and CLK_d. When CLK_d becomes high, and if X remains low, then Y rises to logic "1," and turns off M1. Thus the contention period is over, and the temporary glitch at Out is eliminated. C-Q delay mode takes places when IN make a transition from high to low before CLK becomes low. When CLK becomes low, X rises to logic "1" and Y remains at logic "0" for the entire evaluation cycle. The delay is measured by the falling edge of both CLK and Out: hence the name C-Q delay. D-Q delay mode utilizes the pre-evaluated characteristic of CD logic to enable high-performance operations. In this mode, CLK falls from high to low before IN transit, hence X initially rises to a nonzero voltage level. As soon as IN become logic "0," while Y is still low, then X quickly rises to logic "1." A race condition exists in this case between X and Y. If CLK_d rises much earlier than X and Y will go to logic "1," turn off M1, and result in a false logic evaluation. If CLK_d rises slightly slower than X, then Y will initially rise (thus slightly turns off M1) but eventually settle back to logic "0." CD logic can still perform the correct logic operation in this case, however, its performance is degraded because of M1's reduced current drivability. Therefore, it is important to

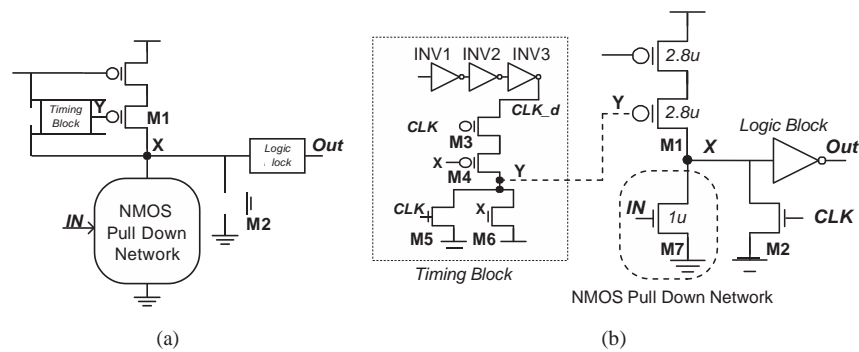


Fig. 3. CD logic (a) block diagram and (b) buffer.

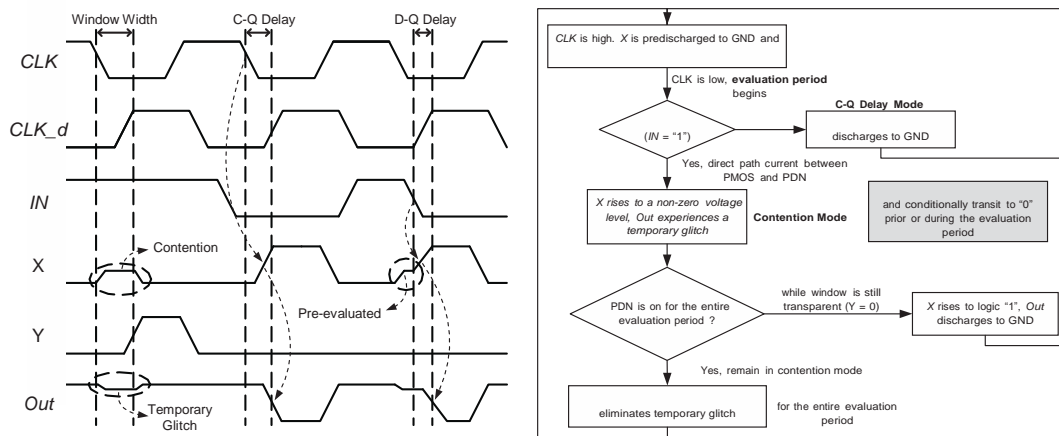


Fig. 4. Timing diagram and flowchart of the proposed CD logic.

TABLE 1
 SUMMARY OF CD LOGIC'S
 OPERATION

Mode	Scenario	Operation
Predischarge	CLK is high	X and Out are predischarged and precharged to GND and VDD, respectively.
Contention	IN = "1" for the entire evaluation period.	Direct path current flows from pMOS to PDN. X rises to a nonzero voltage level and Out experiences a temporary glitch.
C-Q Delay	IN goes to "0" before CLK transits to low.	X rises to logic "1" and Out is Discharged to VDD.
D-Q Delay	IN goes to "0" after CLK transits to low (while window is still open, i.e., Y is still "0").	X initially enters contention mode and later rises to logic "1." Delay is measured from IN to Out.

maintain a sufficient window width under process–voltage–temperature (PVT) variations. Table I presents a summary of CD logic's operations.

Compared to FTL, where the contention lasts for the entire evaluation period, TB effectively reduces CD logic's power consumption during the contention mode. The local window technique in the proposed CD gate allows designers to customize the window width for different logic expressions to achieve minimal power dissipation while not sacrificing

the performance. For instance, a multiple input NAND gate will require a longer window width than a NOR gate because of the larger internal capacitance due to the stacked nMOS transistors. Another advantage of CD logic is that the internal node(X) is always connected to either VDD or GND, thus making the robustness of CD logic comparable to static logic, except during the contention mode.

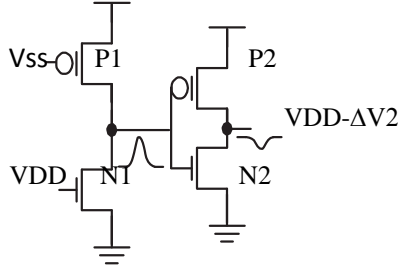


Fig. 5. Simplified schematic of CD logic during contention mode

III. CD LOGIC DESIGN CONSIDERATIONS

A. CD Logic Sizing

The sizing of INV1-3 and M3-M6 in Fig. 3(b) is close to the minimum size so that they do not create a huge area burden. The length of INV1-3 can be altered to provide the required timing window duration based on designer's choices.

1) *CD Logic Versus Pseudo-nMOS*: Both pseudo-nMOS and CD logic are ratioed circuits which rely on the correct pMOS to nMOS strength ratio to perform correct logic operations. pMOS transistor width is often selected to be about one-fourth the strength of the nMOS PDN as a compromise between noise margin and speed in pseudo-nMOS [6]. On the other hand, CD logic always discharges X to GND when CLK is high, therefore, CD logic can be optimized for low-to-high transition only. Hence, pMOS clock transistors in CD logic can be upsized larger to provide more speedup, as long as the output glitch is maintained at an acceptable level.

B. Output Glitch

Fig. 5 depicts a simplified schematic of CD logic during the contention mode, where both transistors $P1$ and $N1$ are on simultaneously and induce a glitch voltage $\Delta V1$, which in turn generates another smaller glitch $\Delta V2$. By design, $\Delta V1$ should be small [i.e., less than the threshold voltage (V_t)]. Hence, $P1$ operates in the saturation region while $N1$ is in the linear region. The current equation is given as

$$\frac{1}{2} \mu_p C_{ox} \frac{W_{p1}}{L_{p1}} (V_{gsp1} - V_{tp})^2 = \mu_n C_{ox} \frac{W_{n1}}{L_{n1}} \left[(V_{gsn1} - V_{tn}) V_{dsn1} - \frac{(V_{dsn1})^2}{2} \right] \quad (1)$$

rearranging (1)

$$\frac{W_{p1}}{4W_{n1}} (V_{DD} - V_{tp})^2 = (V_{DD} - V_{tn}) \Delta V_1 - \frac{(\Delta V_1)^2}{2} \quad (2)$$

V_1 can be found by solving the quadratic equation

$$\Delta V_1 = V_{DD} - V_{tn} - \sqrt{(V_{DD} - V_{tn})^2 - \frac{W_{p1}}{2W_{n1}} (V_{DD} - V_{tp})^2} \quad (3)$$

$$\text{By Taylor expansion, } \sqrt{N^2 + d} = N + \frac{d}{2N} - \frac{d^2}{8N^3} + \frac{d^3}{16N^5} \cdot \dots \approx N + \frac{d}{2N} \quad (4)$$

Assuming $V_{tp} \approx V_{tn}$, (3) can be approximated as

$$\Delta V_1 \approx V_{DD} - V_{tn} - (V_{DD} - V_{tn}) + \frac{W_{p1}(V_{DD} - V_{tp})^2}{4W_{n1}(V_{DD} - V_{tn})} \approx \frac{W_{p1}(V_{DD} - V_{tp})^2}{4W_{n1}} \quad (5)$$

ΔV_2 can also be found through a similar approach. Consider Fig. 5 again transistor $N2$ operates in the subthreshold region while $P2$ is working in the linear mode. Equating the two current equations yields.

$$\frac{W_{n2}}{L_{n2}} I_t e^{\frac{V_{gsn2} - V_{tn}}{\eta V_T}} \left(1 - e^{-\frac{V_{dsn2}}{V_t}} \right) = \mu_p C_{ox} \frac{W_{p2}}{L_{p2}} \left[(V_{gsp2} - V_{tp}) V_{dsp2} - \frac{(V_{dsp2})^2}{2} \right] \quad (6)$$

Where (18), (19)

$$I_t = \mu_p C_{ox} (V_T)^2 e^{1.8}, = 1 + \frac{3T_{ox}}{W d_m}, \quad V_T = \frac{KT}{q} \quad (7)$$

Rearranging (6) gives

$$\frac{W_{n2} I_t e^{\frac{\Delta V_1 - V_{tn}}{\eta V_T}}}{\mu_p C_{ox} W_{p2}} = (V_{DD} - \Delta V_1 - V_{tp}) \Delta V_2 - \frac{(\Delta V_2)^2}{2} \quad (8)$$

Where $e^{-\frac{V_{dsn2}}{V_t}} \approx 0$ since $(V_{DD} - \Delta V_2) \gg V_T$. Solving ΔV_2 then yields

$$\Delta V_2 = V_{DD} - \Delta V_1 - V_{tp} - \sqrt{(V_{DD} - \Delta V_1 - V_{tp})^2 - A e^{\frac{\Delta V_1 - V_{tn}}{\eta V_T}}}$$

Applying taylor's expansion

$$\Delta V_2 \approx V_{DD} - \Delta V_1 - V_{tp} - \left((V_{DD} - \Delta V_1 - V_{tp}) - \frac{A e^{\frac{\Delta V_1 - V_{tn}}{\eta V_T}}}{2(V_{DD} - \Delta V_1 - V_{tp})} \right) \quad (11)$$

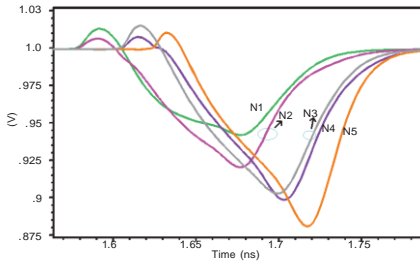


Fig. 6. Simulated output glitch of a five-stage two-input AND gate implemented with CD logic.

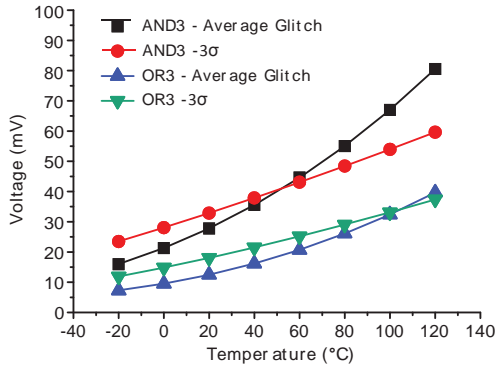


Fig. 7. Temporary glitch mean and standard deviation at the output of three-input CD, AND, and OR gate versus temperature in a Monte Carlo simulation with 7500 iterations.

Finally

$$V_2 \approx \frac{Ae^{\frac{V_1 - V_{tn}}{\eta V_T}}}{2 \frac{DD - 1 - t_p}{V}} \quad (12)$$

Equations (5) and (12) provide several first-order design insights for CD logic. For a given V_1 , designers can quickly estimate the required W_{p1} to W_{n1} ratio. Moreover, V_1 is linearly proportional to the shift of V_t and transistor width in the presence of process variations. When V_1 is sufficiently small, V_2 is approximately zero. As V_1 increases, both the numerator and denominator in 12 contribute to V_2 's exponential increase. In a multistage CD logic circuitry, V_1 of each stage will slowly increase because of the reduced V_{gs} of $N1$ due to V_2 from the preceding stage. This phenomenon is demonstrated in Fig. 6, where the glitch level aggravates as it traverses through a series of two-input AND gate implemented with CD logic. Equation (12) also suggests that V_2 is a strong function of temperature. Fig. 7 illustrates the mean and three standard deviations (3σ) of the temporary glitch at the output of a three-input CD, AND, and OR gate versus temperature. Clearly, as the temperature increases from 20 °C to 120 °C, the 3σ glitch level of a three-input AND gate raises from 55 mV to approximately 140 mV.

C. Power Consumption

Data activity measures how frequent signals toggle and is defined as

$$\text{data activity} = \frac{\# \text{ of signal transitions}}{\# \text{ of signals} \times \# \text{ of clock cycles}}$$

Static logic has an empirical α of 0.1–0.2 [6] and dynamic domino logic has an activity factor of 0.5. While CD logic's α is also 0.5, it always consumes power when it enters the evaluation period. During the evaluation period, CD logic always dissipates power via either dynamic power dissipation (X goes to VDD and Out is discharged to GND) or direct path current (contention mode). While CD logic consumes more power, we believe that CD logic is still an attractive choice in a high-performance full-custom design because: 1) CD logic is only intended to replace the critical path; and 2) power management techniques such as clock gating [20], [21], where the clock connection to idle module is turned off (gated), will significantly reduce CD logic's dynamic power consumption.

D. CD Logic Family

CD logic's LB [Fig. 3(a)] can be modified such that the inverter is replaced by a static gate to achieve even higher performance, since the inverter delay is not wasted. We refer to such a variation as "compound CD logic" (CCD), analogous to the case of CDL of the dynamic domino logic. Another family of CD logic was proposed in [22], where the output inverter is replaced by a dynamic domino logic. The analysis in [22] shows that a 64-bit parallel-prefix adder employing this type of logic is superior to its CDL-based counterpart, however, it requires additional design considerations because of the degraded noise margin.

IV. CD LOGIC CHARACTERIZATION

Unless otherwise specified, all simulation runs in this paper are done in schematic level (transistor netlists), with extracted parasitic capacitance in the Cadence design environment using

65-nm CMOS technology. All the CD logic gates are designed such that the worst case glitch level under 6σ deviation with nominal VDD (1.0 V) is less than 300 mV at 110 °C. The measured power consumption includes clock trees and data buffers, which are both sized to drive a fanout-of-4 (FO4) load. The outputs of all the logic gates are driving an identical 20 fF load. The window duration (width) is defined as the 50% point of the falling edge of CLK to the 50% point of the rising edge of node Y . The delay is measured at the 50% switching point of either the CLK or data to the 50% switching point of the latest output.

In this section, all logic transistors have a 1- μm effective nMOS width. For CD logic, the pMOS CLK transistors' width is 2.4 μm . The transistor sizings are optimized primary for delay, because the main objective of this section is to explore CD logic's performance advantage. The clock and data frequencies are set to 2 GHz.

A. Noise Margin Versus Window Width

Noise margin is defined as the dc noise level at the input generating a false logic evaluation at the output of the same gate and can be computed based on the following formula:

$$\text{Noise Margin} = V_{\text{original}} - V_{\text{noise}} \quad (14)$$

where V_{original} is the expected voltage level without any input

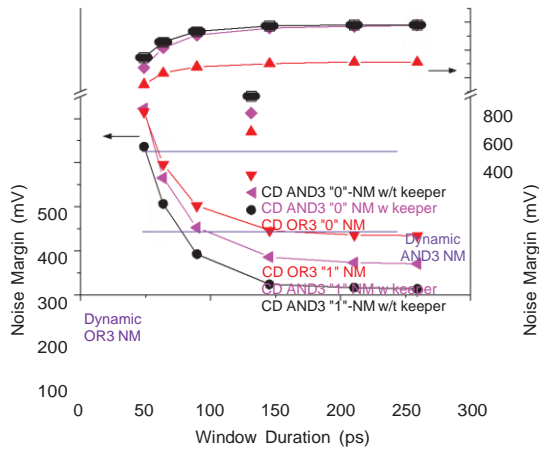


Fig. 8. Simulated logic “1” and “0” noise margin versus window duration for a three-input AND and OR gate.

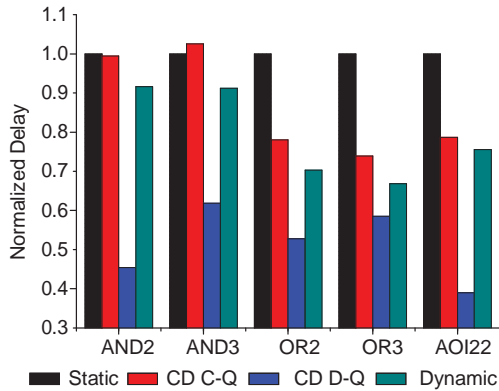


Fig. 9. Normalized delay of five logic expressions implemented in static, dynamic, and CD logic.

causes the false logic evaluation. For CD logic, two types of noise margin are defined: logic “1” and “0” noise margins. Logic “1” noise margin refers to the input dc noise level that causes the CD logic to fail to remain in the contention mode. If IN [Fig. 3(b)], which is supposed to be at full VDD, is now degraded due to noise, then the glitch level at X may be too high such that Out is falsely discharged. In this case, the noise margin can be calculated as $1V - V_{in}$, where V_{in} is V_g of M7. Similarly, logic “0” noise margin refers to the input dc noise level that causes the CD logic to fail evaluating. In this case, if an input which is supposed to be at GND is now much higher due to noise, the contention between M1 and M7 will cause X to settle at an intermediate voltage instead of VDD. When CLK_d rises to VDD (window closes), Y will also be charged up through M3 and M4, since M3 is on and M4 is partially on because X is not at VDD. If the voltage level at X is too low, then Y will be charged to VDD through positive feedback and X will be discharged to GND through M7, which is driven by the noise source.

Fig. 8 shows the simulated worst case logic “1” and “0” noise margin for a three-input AND gate and OR gate implemented with CD and dynamic domino logic. The CD logic’s logic “0” noise margin is always much higher than the logic “1” noise margin, suggesting that CD logic is more robust during the C–Q delay and the D–Q delay than the contention mode. Moreover, as the window width prolongs,

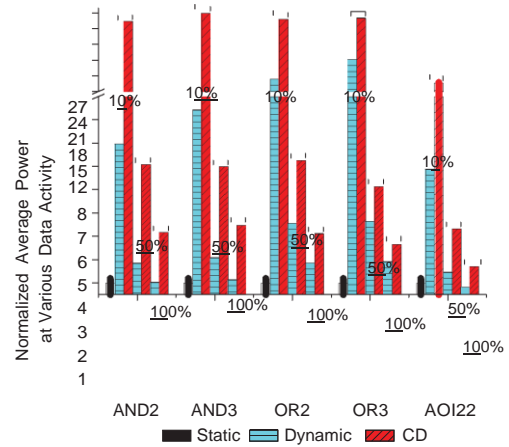


Fig. 10. Normalized average power of five logic expressions at various data activities implemented in static, dynamic, and CD logic.

Logic “0” noise margin improves while logic “1” noise margin degrades for both logic types. Therefore, reducing the window duration not only minimizes the power consumption but also improves CD logic’s overall robustness. For noise-margin-sensitive applications, a minimum-size nMOS keeper (gate connected to Out, drain connected to X) can be added to improve its overall robustness. In this case, the minimum-size keeper improves logic “1” noise margin by approximately 60 mV with virtually no degradation in logic “0” noise margin.

B. CD Logic Performance

Figs. 9 and 10 illustrate the normalized delay and average power consumption of static, dynamic, and CD logic, respectively, in five logic expressions with various input data activities. The average power is calculated by summing up the power consumption of every possible input vector and then dividing it by the number of input vector combinations.

CD logic demonstrates superior performance, especially for complicated logic expressions, such as $Y = AB + CD$ (AOI22), in the D-Q mode due to the pre-evaluated characteristic. This is demonstrated in Fig. 11, where CD logic is approximately two times faster than dynamic domino logic. This is contributed by: 1) the pre-evaluated characteristic; and 2) the less number of transistors in the critical path (3N1P for dynamic, while only 2P1N for CD logic). On the other hand, CD logic’s performance is only approximately the same as or even worse than that of dynamic domino logic during the C–Q mode. Therefore, it is advantageous to implement CD logic in a single-cycle multistage datapath because then the pre-evaluated feature (D–Q delay) of CD logic can be fully utilized. The power consumption of CD logic at 50% data activity is at least $3 \times$ and $5 \times$ higher than that of static logic in AOI22 and the rest of logic expressions, respectively. This suggests that CD logic should be used only to replace the critical path in any circuit block, since it is not energy efficient to implement any system with CD logic only. Table II summarizes the total transistor width of static, dynamic, and CD logic. Despite CD logic’s additional transistor overhead, the average area of CD logic is 13% smaller and 4.5% larger than that of static and dynamic domino logic, respectively.

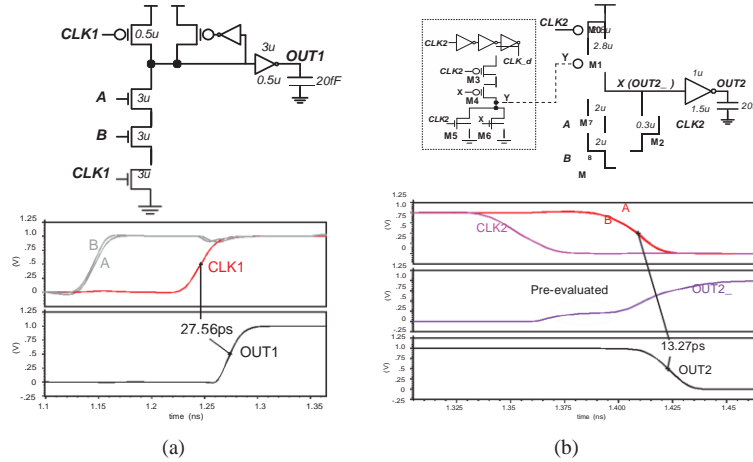


Fig. 11. Schematic and timing waveform of (a) dynamic and (b) CD logic.

 TABLE II
 STATIC, DYNAMIC, AND CD LOGIC AREA COMPARISON

	Total transistor width (μm)			Number of transistors		
	Static	Dynamic	CD	Static	Dynamic	CD
AND2	11	13.6	14.96	6	7	17
AND3	18	20.9	19.96	8	8	18
OR2	13	10.6	12.96	6	7	17
OR3	24	12.6	13.96	6	7	18
AOI22	27	19.6	18.96	10	9	19
Average	18.6	15.46	16.16	7.2	7.6	17.8

V. PERFORMANCE ANALYSIS

A. 8-bit Ripple Carry Adders (RCAs)

The simulation setup in this section is similar to that of Section IV. Three 8-bit RCAs using static, dynamic, and CD logic style are simulated to compare their performances. An RCA with FTL on the critical path is also implemented, however, our analysis indicates that FTL-based RCA would generate false outputs at the later bits because of the false evaluation phenomenon described earlier. NP-FTL (equivalent to NP-domino, where nMOS-FTL and pMOS-FTL alternate) is also difficult to realize because the output glitch is significant and easily exceeds 500 mV under process variations.

The basic static full adder (FA) is implemented with 28 transistors with sizing strongly in favor of C_{out} computation [6]. The main purpose of this 8-bit RCA is to demonstrate CD logic's performance advantage and to discuss the design considerations that should be taken into account when using CD logic. A more energy-efficient pass-transistor FA design [23] will be implemented in the subsequent analysis to provide a more realistic comparison.

Only the timing-critical carry generation is replaced with dynamic and CD logic, while noncritical sum computation remains static in all three RCAs. Ten-thousand random input vectors are applied to RCAs to compute the average power consumption. The clock timing is designed in such a way that all the CD logic gates except the first stage are operated in the

D-Q mode with a window duration of approximately 115 ps.² Fig. 12(a) depicts the RCA block diagram and FA schematic. Fig. 12(b) shows the corresponding worst case timing diagram for CD logic, which occurs when $\{C_{\text{in}}, A_0 \cdots A_7, B_0 \cdots B_7\} = \{0, 0 \cdots 0, 1 \cdots 1\}$.

1) *Design Considerations in a Multistage System:* Fig. 12(b) provides several insights into designing single-cycle multistage CD circuitries. When CD logic is to be used with other logic styles and when the gate preceding the CD logic is not a precharge type logic (i.e., dynamic domino logic), then the inputs (*Data*) can only make transitions when all CD logic gates are in the predischarge mode (i.e., CLK1–4 are high). CD logic may suffer from additional power consumption due to the possible direct path current during the predischarge mode. Consider a CD-based RCA with the worst case input vector, FA0-2's CD logic carry circuitries enter predischarge mode when CLK1 goes to high. The internal nodes before the output inverter of all CD logic gates are all discharged to logic "0" by nMOS clock transistors, and the outputs (C_1 to C_3) are charged to logic "1." If C_3 becomes logic "1" before FA3 enters predischarge mode (i.e., CLK2 is still high), then a direct path takes place.³ To avoid this condition, it is necessary for $T_{\text{discharge}} \geq T_{\text{delta}}$, where $T_{\text{discharge}}$ is the time that the CD logic takes to charge its output and T_{delta} is the delay between two adjacent clock signals (CLK2 to CLK1, or CLK3 to CLK2, etc.).

2) *CD Logic Sizing Strategy:* To guarantee a 6σ glitch level of 300 mV at 110 °C, the following sizing strategy is employed.

- 1) An equally weighted variable is assigned to the width of CD logic's pMOS pull-up transistors.

²The window duration is a function of the logic expression, the number of preceding stages that are driving by the same phase clock signal, the maximum glitch level constraint, and the robustness of the overall system. Extensive simulation results have indicated that a window duration of 115 ps provides excellent delay and power performances while maintaining a sufficient timing margin against PVT and transistors mismatch variations (Table VII).

³Consider the CD carry generation circuitry shown in Fig. 12(a), under worst case vector condition $B = 1$ and $A = 0$. If input C (C_{in} from the preceding stage) rises to logic "1" (originally at logic "0") before CLK is high, then both pMOS and nMOS transistors are on.

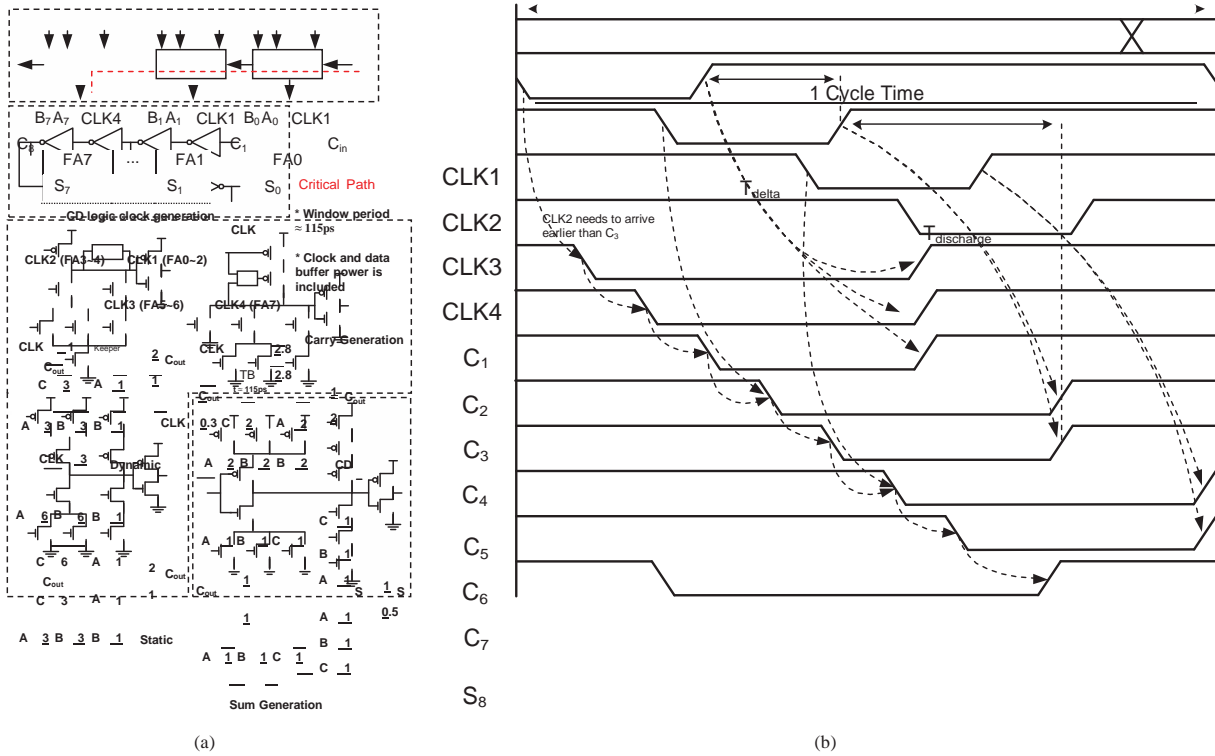


Fig. 12. RCA (a) block diagram and (b) timing diagram implemented with CD logic.

TABLE III
RCA PERFORMANCE COMPARISON

	Static			Dynamic			CD		
	10%	50%	100%	10%	50%	100%	10%	50%	100%
Data activity									
Delay (ps)	369.4 (1.00)			292.6 (0.79)			224.4 (0.61)		
Power (μ W)	50.95	254.77	509.54	142.70	336.05	401	231.85	533.96	602.82
Power-delay product (PDP) (fJ)	18.8	94.1	188.2	41.8	98.3	117.3	52	119.8	135
Energy-delay product (EDP) (fJ·ps)	6944	34761	69521	12231	28763	34322	11669	26883	30294

- 2) The entire circuitry (i.e., 8-bit RCA) is then simulated under typical corner at 110 °C to determine the glitch level. Extensive simulation results reveal that, if this glitch level is approximately 65 mV, then the 6σ glitch level will be less than 300 mV.
- 3) Iterative simulations are performed by sweeping this variable until the glitch level is around 65 mV.

The equally weighted scheme clearly may not be the optimal solution. However, different sizing schemes have been explored and simulation results indicate that no apparent performance improvement is achieved compared to the sizing strategy described above.

3) *RCA Performance*: Table III compares static, dynamic, and CD logic RCAs with various figures of merits at different data activity factors. CD-based RCA is approximately 39 and 23% faster than the static and dynamic counterparts, respectively. On the other hand, the power consumption of CD logic ranges from $4.55 \times$ to $1.18 \times$ higher than that of static logic. In terms of the PDP, CD logic is $2.78 \times$ more and $0.72 \times$ less than static logic at 10 and 100% data activity, respectively. CD logic provides a speed advantage that logic styles such as static and dynamic find difficult to reach. Therefore, CD logic is suitable in a system where performance is the most critical factor.

B. 32-bit Carry Lookahead Adder (CLA)

We implement 32-bit CLAs to further analyze CD logic's performance. The detailed operations of CLA are described in [6] and the schematic is displayed in Fig. 13. The 32-bit CLA uses eight 4-bit FAs with dedicated circuitry to facilitate carry generation. The energy-efficient FA used in this analysis utilizes pass transistor logic styles with only 24 transistors for sum generation [23]. For the carry generation, only the critical path is replaced with different logic style. The maximum fan-in is limited to four, except in the case of dynamic domino logic due to the footer transistor. In this case, the 4-bit critical carry generation path of CLA is

$$G_{3:0} = G_3 + P_3(G_2 + P_2(G_1 + P_1(G_0))) \quad (15)$$

where G and P are the generate ($A \cdot B$) and propagate ($A \oplus B$) signals, respectively. CDL and CCD logic are implemented to reduce the number of fan-ins. One can utilize the inversion property and rearrange 15 to

$$\begin{aligned} G_{1:0} &= G_1 + P_1 G_0, & P_{2:0} &= P_2 P_1 \\ G_{2:0} &= G_2 + P_2 G_1, & G_{3:0} &= \overline{C}_{3:2}(P_{3:2} + G_{1:0}). \end{aligned} \quad (16)$$

Therefore, a maximum fan-in of two and three can be achieved with CCD logic (Section III-D) and CDL, respectively. The critical pMOS transistors' width of CCD logic is slightly

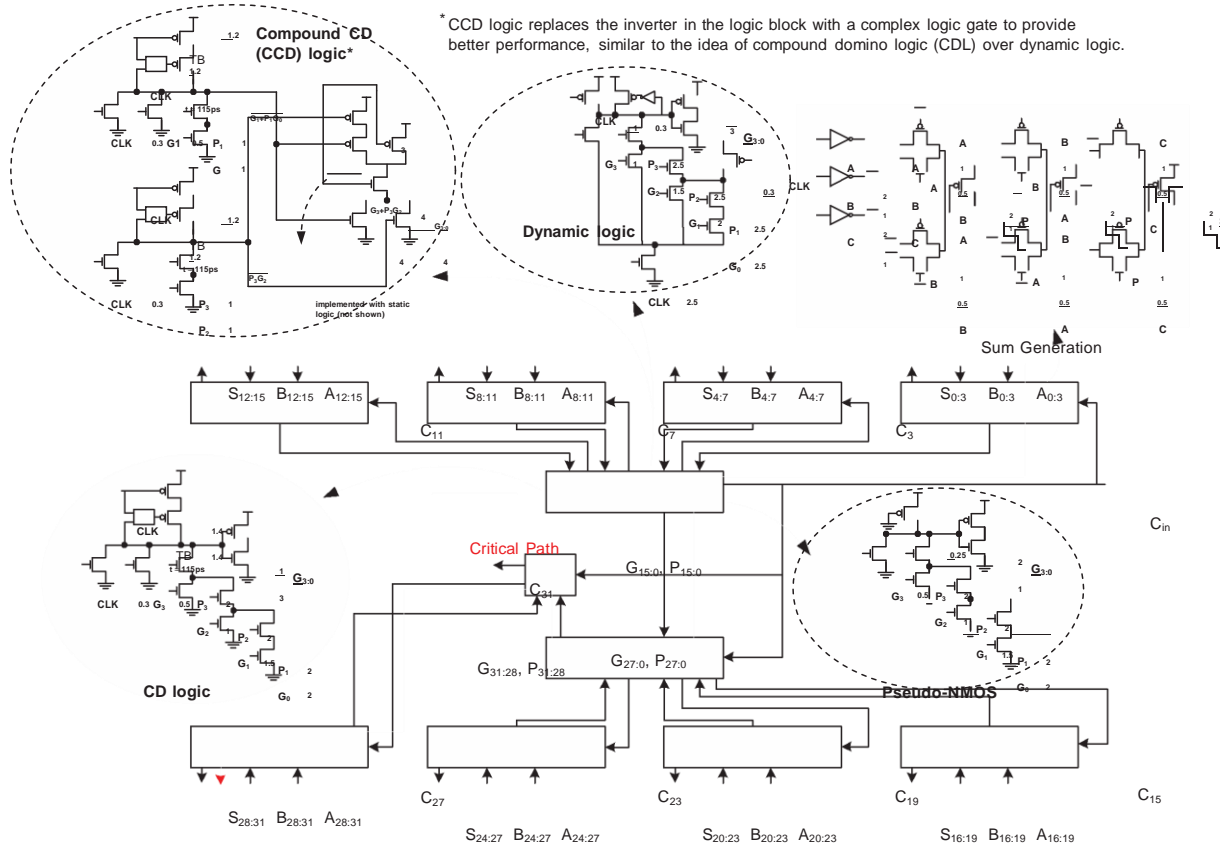


Fig. 13. 32-bit CLA.

TABLE IV
32-BIT CLA PERFORMANCE COMPARISON

Data activity	100%			50%			25%			10%			Worst case leakage (μA)	
	Delay (ps)	Power (mW)	PDP (pJ)	EDP (pJ-ps)	Power (mW)	PDP (pJ)	EDP (pJ-ps)	Power (mW)	PDP (pJ)	EDP (pJ-ps)	Power (mW)	PDP (pJ)		EDP (pJ-ps)
Static	448 (1.00)	5.13	2.3	1030	1.94	0.87	390	0.99	0.45	199	0.42	0.19	85.1	32.9
Dynamic	316 (0.71)	5.27	1.67	526	2.22	0.7	222	1.32	0.42	132	0.8	0.25	79.8	32.1
CDL	287 (0.64)	5.29	1.52	437	2.21	0.63	182	1.33	0.38	110	0.81	0.23	66.7	32.7
Pseudo-nMOS	313 (0.70)	5.34	1.67	523	2.21	0.69	216	1.25	0.39	122	0.68	0.21	66.3	551.2
CD logic	272 (0.61)	5.02	1.37	371	2.31	0.63	171	1.43	0.39	106	0.90	0.25	66.8	33.5
CCD logic	239 (0.53)	5.09	1.22	291	2.34	0.56	134	1.46	0.35	84	0.94	0.22	53.5	33.4

smaller than that of CD logic to satisfy the 300-mV glitch constraint because the pull-up path in the LB now consists of two pMOS transistors. Footless dynamic domino logic cannot be applied in this analysis because not all the circuits are implemented with dynamic domino logic. Therefore, some of the inputs to the dynamic domino logic in the critical path can come from noncritical static gates. In order to satisfy the monotonicity requirement and to avoid the possible direct path current, a footer transistor is required for all dynamic domino logics. On the other hand, if the entire 32-bit CLA is implemented with dynamic domino logic, then the footless scheme can be applied. However, simulation results indicate that the power consumption in this case is much higher than that of the current setup, thus making it a less attractive design. Table IV summarizes the simulation results for the 32-bit

CLAs. Power consumption is calculated with 5000 random input vectors. The performance enhancement of CD and CCD logic is evident in this case, with 39 and 47% speedup over static design, respectively. Both CD and CCD logic are also faster than pseudo-nMOS, primarily because of the larger effective pMOS width. The worst case leakage of all the designs is comparable except the case of pseudo-nMOS, which is caused by the contention between nMOS PDN and the weak pMOS pull-up transistor. In this case, pseudo-nMOS's leakage (static power dissipation) is at least $15 \times$ higher than the rest of the designs.

Figs. 14–16 show the normalized power, PDP, and EDP of all the CLAs analyzed in this paper, respectively. At 10% (100%) α , the power consumption of CD logic is $2.1 \times (1.05 \times)$ Higher than the static logic.

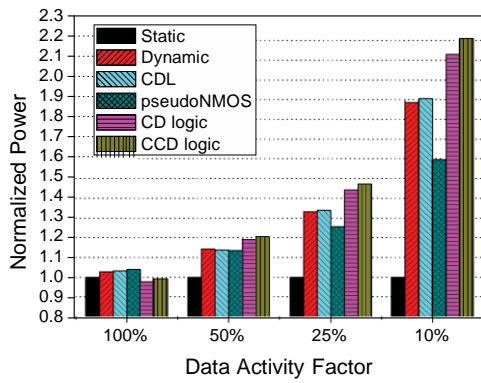


Fig. 14. Normalized power of 32-bit CLAs.

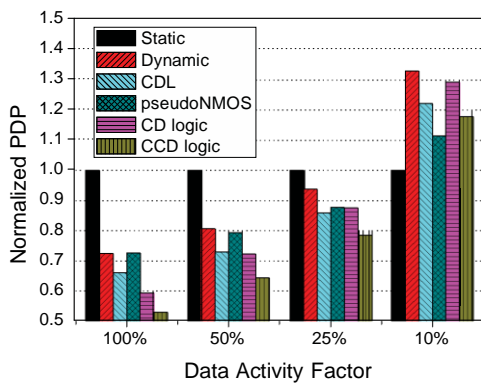


Fig. 15. Normalized PDP of 32-bit CLAs.

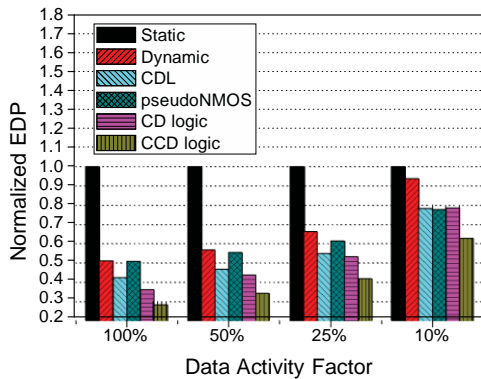


Fig. 16. Normalized EDP of 32-bit CLAs.

at 10%. While higher than CCD logic, the PDP of CD logic is comparable to CDL and pseudo-nMOS and is lower than the rest of the designs. At 25% α , EDP reduction of CD and CCD logic from other designs is at least 4 and 24%, respectively. At 10% data activity, CCD logic achieves the lowest EDP with at least 19% improvement. Notice that the power consumption of a CLA implemented with CD logic is lower than that of a CLA with dynamic domino logic at 100% data activity. This is because the width (1 μm) of CD logic's pull-up pMOS transistors in this CLA is much smaller than that (2.4 μm , Section IV) of CD logic in a single-stage logic gate. Hence the power consumption of dynamic domino logic is higher

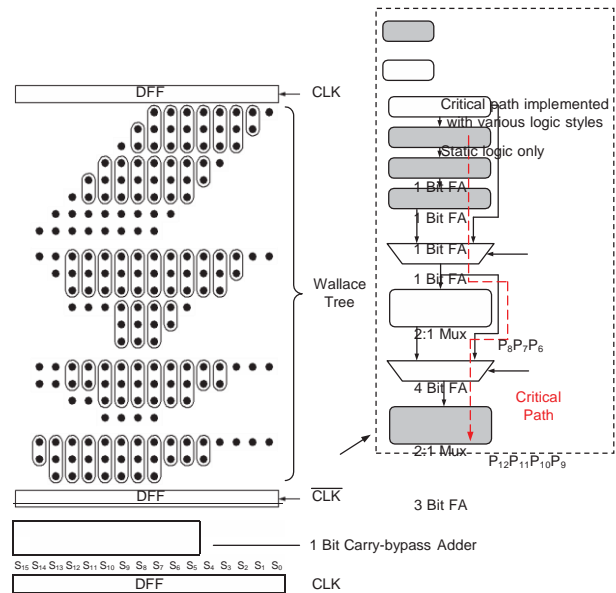


Fig. 17. 8-bit Wallace tree multiplier.

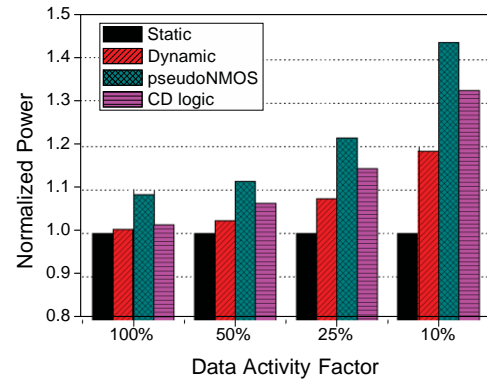


Fig. 18. Normalized power of 8-bit multipliers.

TABLE V
CD AND CCD LOGIC GLITCH IN 32-bit CLAs

Temp. ($^{\circ}\text{C}$)	CD logic			CCD logic		
	Mean (mV)	σ (mV)	Mean + 6σ (mV)	Mean (mV)	σ (mV)	Mean + 6σ (mV)
85	65.3	23.2	204.5	63.6	26.2	220.8
110	88.5	29.8	267.3	86.8	36.1	303.4

than that of CD logic due to the higher internal capacitance at 100% data activity. Similar reasoning can easily apply to a CLA with CCD logic.

Table V summarizes the mean and σ of CD and CCD logic's worst glitch level in a Monte Carlo simulation with 2000 samples. The worst case glitch is calculated by summing up the mean and the extrapolated six σ deviation.⁴ CCD logic exhibits higher worst case glitch level than CD logic at both 85 $^{\circ}\text{C}$ and 110 $^{\circ}\text{C}$, despite its already lower critical pMOS effective width. Both designs are approximately within the glitch constraint set earlier, and demonstrate that they are still able to function properly under extreme process and temperature conditions.

⁴It is assumed that the glitch variation as a result of process variations follows Gaussian distribution.

TABLE VI
8-bit MULTIPLIER PERFORMANCE COMPARISON

Data activity	100%				50%			25%			10%			Worst case
	Delay (ps)	Power (mW)	PDP (pJ)	EDP (pJ·ps)	Power (mW)	PDP (pJ)	EDP (pJ·ps)	Power (mW)	PDP (pJ)	EDP (pJ·ps)	Power (mW)	PDP (pJ)	EDP (pJ·ps)	leakage (μA)
Static	404 (1.00)	3.52	1.42	575	2.29	0.93	375	1.29	0.52	211	0.67	0.27	109	88.78
Dynamic	294 (0.73)	3.57	1.05	309	2.36	0.7	205	1.39	0.41	121	0.80	0.23	69	89.09
Pseudo-nMOS	292 (0.72)	3.82	1.11	325	2.56	0.75	218	1.57	0.46	134	0.96	0.28	82	619.6
CD logic	243 (0.60)	3.59	0.87	212	2.46	0.60	145	1.49	0.36	88	0.88	0.22	52	89.99

TABLE VII
PVT AND MONTE CARLO PERFORMANCE ANALYSIS OF THE CD AND CCD LOGIC-BASED DESIGNS

Corner	FF				FS				SF				SS				Monte Carlo	
	110		-30		110		-30		110		-30		110		-30			
Temperature ($^{\circ}C$)	VDD (V)																mean	σ
	1.1	0.9	1.1	0.9	1.1	0.9	1.1	0.9	1.1	0.9	1.1	0.9	1.1	0.9	1.1	0.9	226	16.2
8-bit RCA (CD) (ps)	152	199	142	197	182	244	178	265	164	220	152	217	262	369	249	392	274	17.8
32-bit CLA (CD) (ps)	189	238	172	229	222	288	206	289	205	259	186	248	321	439	294	437	274	17.8
32-bit CLA (CCD) (ps)	157	200	147	199	190	250	185	263	169	218	156	214	280	388	266	405	240	18.2
8-bit multiplier (CD) (ps)	211	229	208	228	223	247	219	249	216	236	212	235	259	327	251	347	244	7

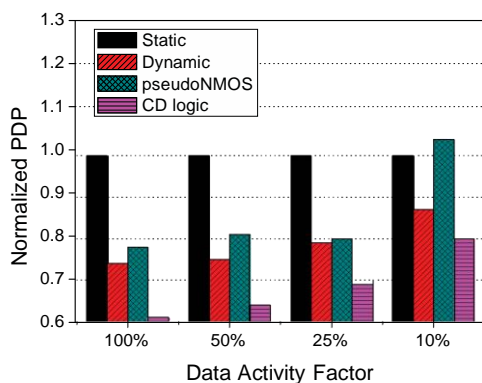


Fig. 19. Normalized PDP of 8-bit multipliers.

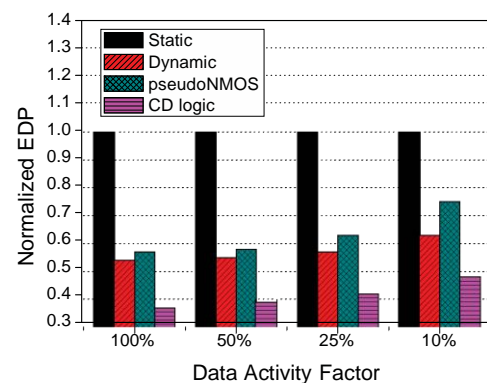


Fig. 20. Normalized EDP of 8-bit multipliers.

C. 8-bit Wallace Tree Multiplier

Single-cycle two-phase 8-bit Wallace tree multipliers are implemented and analyzed. The first phase (CLK is high) is a Wallace tree utilizing 3:2 compressors to reduce the number of partial products, and during the second phase final addition is carried out by a 11-bit carry bypass adder, as shown in Fig. 17. Only the critical path of the final adder is implemented with various logic styles with the exception of multiplexors, while the rest of the circuits remain static. Simulation setups are similar to that of 32-bit CLAs.

Table VI summarizes the performance results of 8-bit multipliers and Figs. 18–20 illustrate the normalized power, PDP, and EDP of the various multipliers under different data activities, respectively. CD logic achieves a similar speedup (40%) over static logic compared to 32-bit adders. At 25% α , CD logic consumes 16% more power, but is 30 and 58% more PDP- and EDP-efficient than static logic, respectively. In 8-bit multipliers, because the critical path is only a small portion of the entire circuitry, CD logic has the lowest PDP and EDP values among all the logic styles across all data activities. CCD and CDL logic are not included in this analysis because they are not particularly suitable for this

setup. This is because G and P signals are not generated in this case, instead, direct inputs (A , B) similar to 8-bit RCA are used to compute the carry. Finally, Table VII shows the PVT analysis and Monte Carlo simulation results (2000 iterations, 27 $^{\circ}C$) of the proposed CD and CCD logic-based designs. All the designs are functional under extreme PVT and transistors mismatches and variations, thereby demonstrating the proposed CD logic's robustness.

VI. CONCLUSION

A new high-performance logic style with CD characteristic and self-reset circuitry was proposed. The pre-evaluated feature of CD logic makes it particularly suitable in a circuit block where a unique critical path exists and performance is the primary concern. Performance analysis of 8-bit RCAs reveals that CD logic is 39 and 23% faster than static and dynamic domino logic, respectively. Simulation results of 32-bit CLAs show similar speed advantage of CD logic compared to static logic. In this setup, CCD logic achieves lowest PDP at all data activity except at 10%. Also, CCD logic achieves the best EDP results, with 66% (37%) reduction compared to static logic at 50% (10%) data activity. The 6σ

worst case glitch for CD and CCD logic at 110 °C are 220.8 and 303.4 mV, respectively.

CD logic's advantages in terms of delay and EDP were also demonstrated in 8-bit Wallace tree multipliers. Compared to 32-bit adders, CD logic achieves a similar delay improvement, but has an even better EDP reduction, primarily because the final adder which makes up the critical path of the multiplier is a relatively small circuit block of the overall circuitry. At 25% α , CD logic is 52, 25, and 37% more EDP-efficient than static, dynamic, and pseudo-nMOS logic, respectively.

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